

2019 2nd International Conference
on Smart Materials Applications

ICSMA 2019

<http://icsma.org>

TOKYO, JAPAN

JANUARY 19-22, 2019

**MORITO MEMORIAL HALL
TOKYO UNIVERSITY OF SCIENCE,
KAGURAZAKA CAMPUS**



1. Template: IOP-Template.doc

2. Submission:

a. by Email: icsma@saise.org

b. by Easychair:

<https://easychair.org/conferences/?conf=icsma2019>



All submissions will be peer reviewed, the registered and presented papers will be published into IOP Conference Series: Materials Science and Engineering

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Topics of interest include (but not limited to) the following:

Materials Science and Engineering

Materials Properties, Measuring Methods and Applications

Methodology of Research and Analysis and Modeling

Materials Manufacturing and Processing

More details please kindly check:
<http://icsma.org/cfp.html>



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Submission Deadline: 15-October-2018

Acceptance Notice: 05-November-2018

Registration Due: 25-November-2018



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